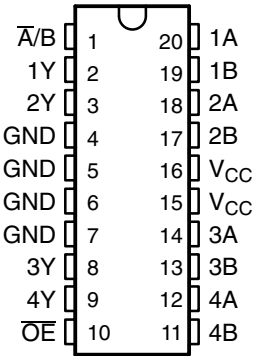
74AC11257
QUADRUPLE 2-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER WITH 3-STATE OUTPUTS

SCAS049C – MARCH 1989 – REVISED MAY 2004

- **3-State Outputs Interface Directly With System Bus**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise**
- **500-mA Typical Latch-Up Immunity at 125°C**
- **Provides Bus Interface From Multiple Sources in High-Performance Systems**

DB, DW, N, OR PW PACKAGE
(TOP VIEW)



description/ordering information

This device is designed to multiplex signals from 4-bit data sources to four output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable ($\overline{OE}$) input is at a high logic level.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	74AC11257N	74AC11257N
	SOIC – DW	Tube	74AC11257DW	AC11257
		Tape and reel	74AC11257DWR	
	SSOP – DB	Tape and reel	74AC11257DBR	AE257
	TSSOP – PW	Tube	74AC11257PW	AE257
		Tape and reel	74AC11257PWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS				OUTPUT Y
$\overline{OE}$	SELECT A/B	DATA A	DATA B	
H	X	X	X	Z
L	L	L	X	L
L	L	H	X	H
L	H	X	L	L
L	H	X	H	H

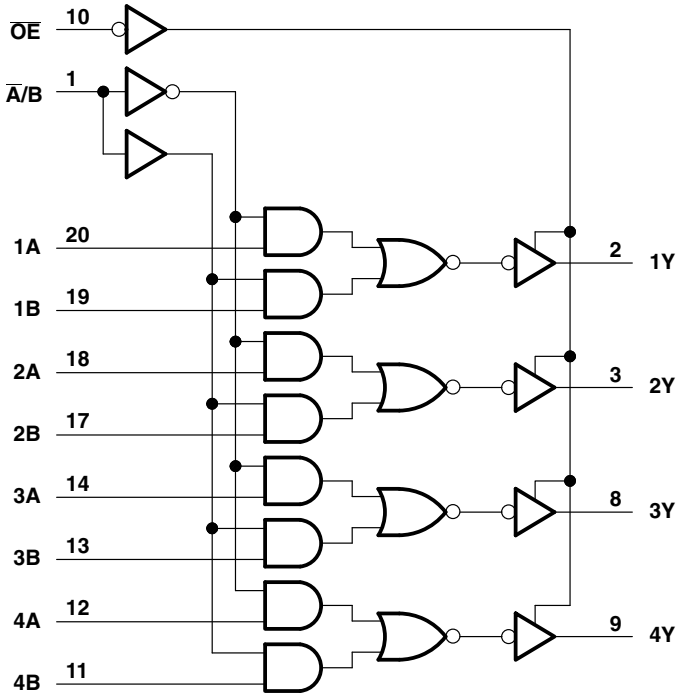


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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) . . . . . ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±100 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package . . . . . 70°C/W
DW package . . . . . 58°C/W
N package . . . . . 60°C/W
PW package . . . . . 83°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		3	5	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1			V
		V_{CC} = 4.5 V	3.15			
		V_{CC} = 5.5 V	3.85			
V_{IL}	Low-level input voltage	V_{CC} = 3 V			0.9	V
		V_{CC} = 4.5 V			1.35	
		V_{CC} = 5.5 V			1.65	
V_I	Input voltage		0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V			–4	mA
		V_{CC} = 4.5 V			–24	
		V_{CC} = 5.5 V			–24	
I_{OL}	Low-level output current	V_{CC} = 3 V			12	mA
		V_{CC} = 4.5 V			24	
		V_{CC} = 5.5 V			24	
$\Delta t/\Delta v$	Input transition rise or fall rate				10	ns/V
T_A	Operating free-air temperature		–40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V_{OH}	I_{OH} = –50 μA		3 V	2.9			2.9		V
			4.5 V	4.4			4.4		
			5.5 V	5.4			5.4		
	I_{OH} = –4 mA		3 V	2.58			2.48		
	I_{OH} = –24 mA		4.5 V	3.94			3.8		
			5.5 V	4.94			4.8		
	I_{OH} = –75 mA†		5.5 V				3.85		
V_{OL}	I_{OL} = 50 μA		3 V			0.1		0.1	V
			4.5 V			0.1		0.1	
			5.5 V			0.1		0.1	
	I_{OL} = 12 mA		3 V			0.36		0.44	
	I_{OL} = 24 mA		4.5 V			0.36		0.44	
			5.5 V			0.36		0.44	
	I_{OL} = 75 mA†		5.5 V					1.65	
I_{OZ}	V_O = V_{CC} or GND		5.5 V			±0.5		±5	μA
I_I	V_I = V_{CC} or GND		5.5 V			±0.1		±1	μA
I_{CC}	V_I = V_{CC} or GND,	I_O = 0	5.5 V			8		80	μA
C_i	V_I = V_{CC} or GND		5 V		3.5				pF
C_o	V_O = V_{CC} or GND		5.5 V		8				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	Y	1.5	5.6	8.1	1.5	8.9	ns
t_{PHL}			1.5	6.2	9	1.5	10.1	
t_{PLH}	$\overline{A}$/B	Any Y	1.5	6.1	9.2	1.5	10.2	ns
t_{PHL}			1.5	6.6	10	1.5	11.2	
t_{PZH}	$\overline{OE}$	Any Y	1.5	5.6	8.2	1.5	9.1	ns
t_{PZL}			1.5	7.5	10.4	1.5	11.8	
t_{PHZ}	$\overline{OE}$	Any Y	1.5	5.6	7.6	1.5	8.3	ns
t_{PLZ}			1.5	6.2	8.8	1.5	9.6	

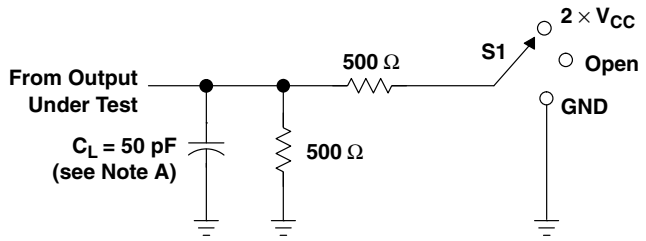
switching characteristics, over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A or B	Y	1.5	3.6	5.8	1.5	6.4	ns
t_{PHL}			1.5	4.1	6.5	1.5	7.2	
t_{PLH}	$\overline{A}$/B	Any Y	1.5	4	6.5	1.5	7.2	ns
t_{PHL}			1.5	4.4	7.1	1.5	7.9	
t_{PZH}	$\overline{OE}$	Any Y	1.5	3.8	5.9	1.5	6.5	ns
t_{PZL}			1.5	5	7.6	1.5	8.6	
t_{PHZ}	$\overline{OE}$	Any Y	1.5	4.5	6.4	1.5	7.6	ns
t_{PLZ}			1.5	4.8	6.9	1.5	7.6	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

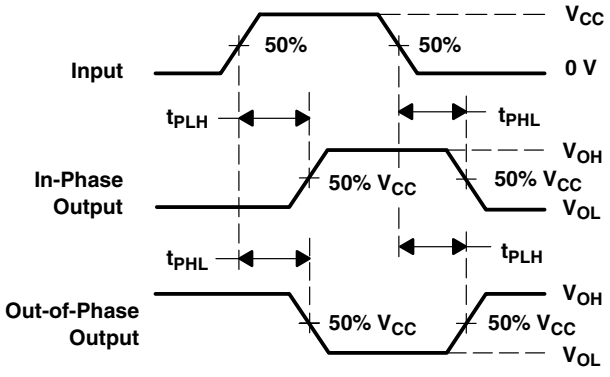
PARAMETER			TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled	C_L = 50 pF,	f = 1 MHz	37	pF
		Outputs disabled			11	

PARAMETER MEASUREMENT INFORMATION

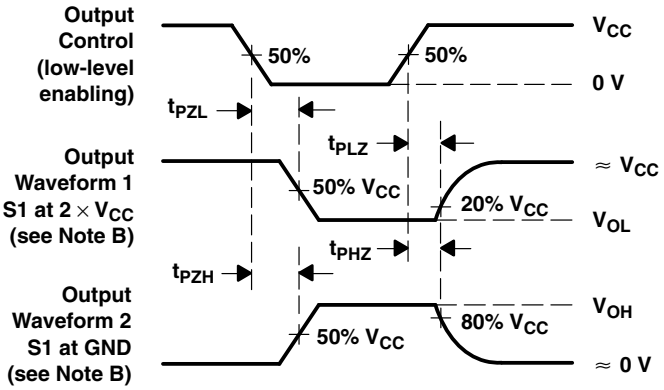


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 3 ns, t_f = 3 ns.
D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74AC11257DW	Active	Production	SOIC (DW) | 20	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC11257
74AC11257DW.A	Active	Production	SOIC (DW) | 20	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC11257
74AC11257N	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	74AC11257N
74AC11257N.A	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	74AC11257N
74AC11257PW	Active	Production	TSSOP (PW) | 20	70 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AE257
74AC11257PW.A	Active	Production	TSSOP (PW) | 20	70 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AE257

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

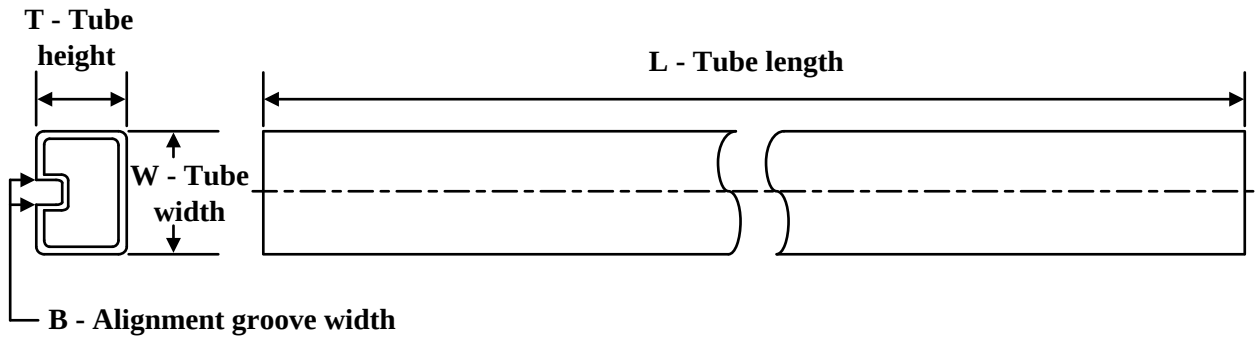
(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TUBE



*All dimensions are nominal

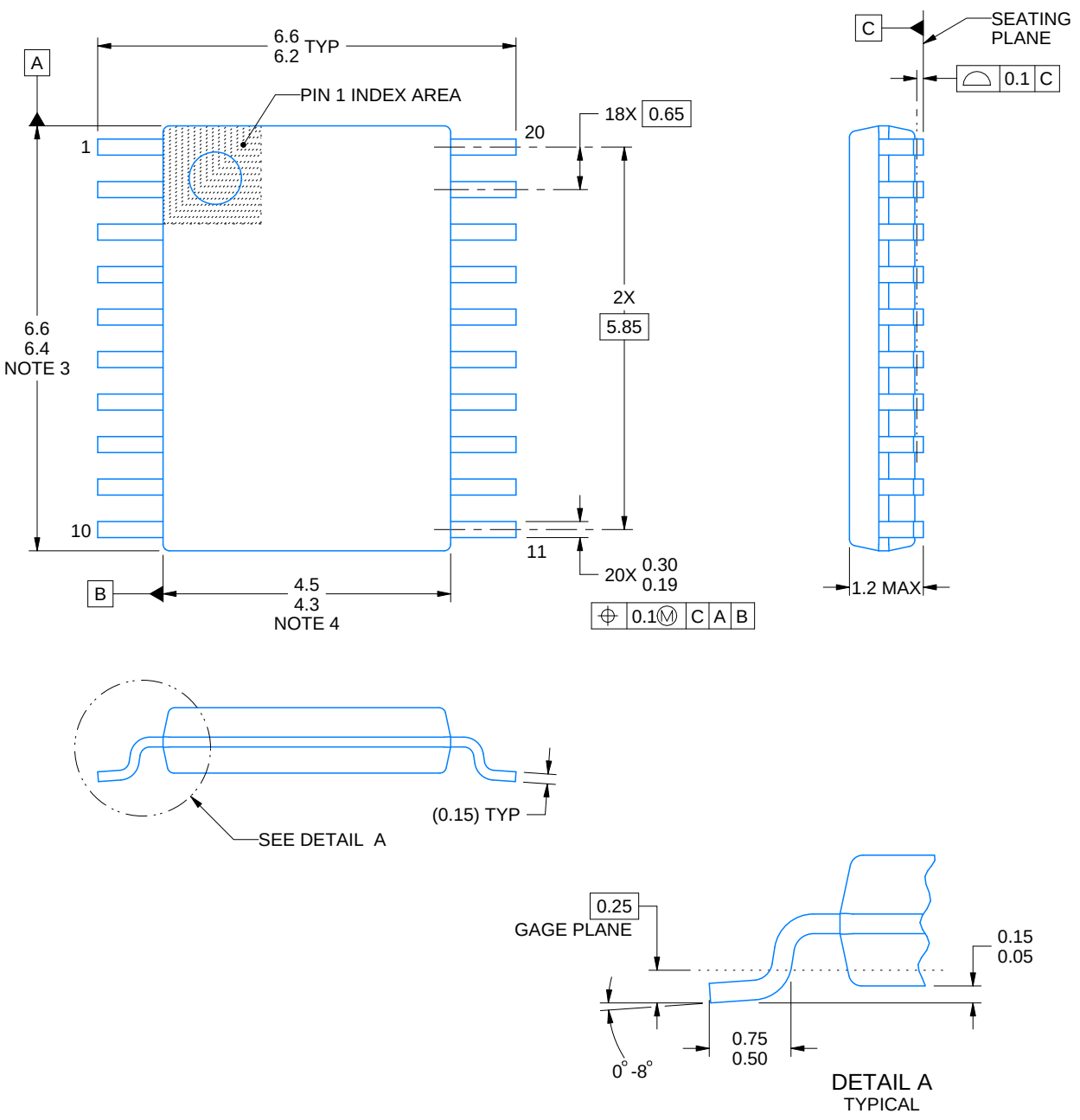
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74AC11257DW	DW	SOIC	20	25	507	12.83	5080	6.6
74AC11257DW.A	DW	SOIC	20	25	507	12.83	5080	6.6
74AC11257N	N	PDIP	20	20	506	13.97	11230	4.32
74AC11257N.A	N	PDIP	20	20	506	13.97	11230	4.32
74AC11257PW	PW	TSSOP	20	70	530	10.2	3600	3.5
74AC11257PW.A	PW	TSSOP	20	70	530	10.2	3600	3.5

PACKAGE OUTLINE

PW0020A

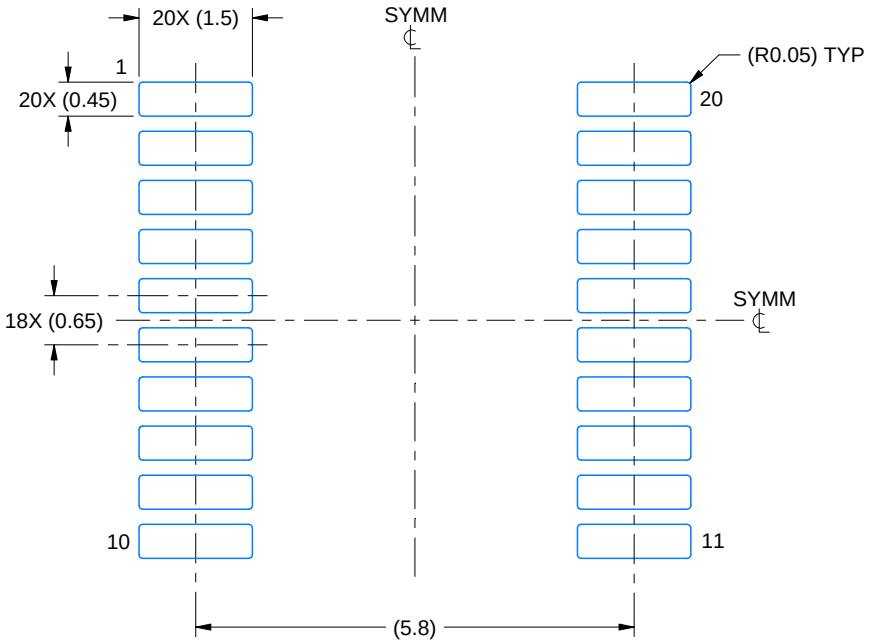
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

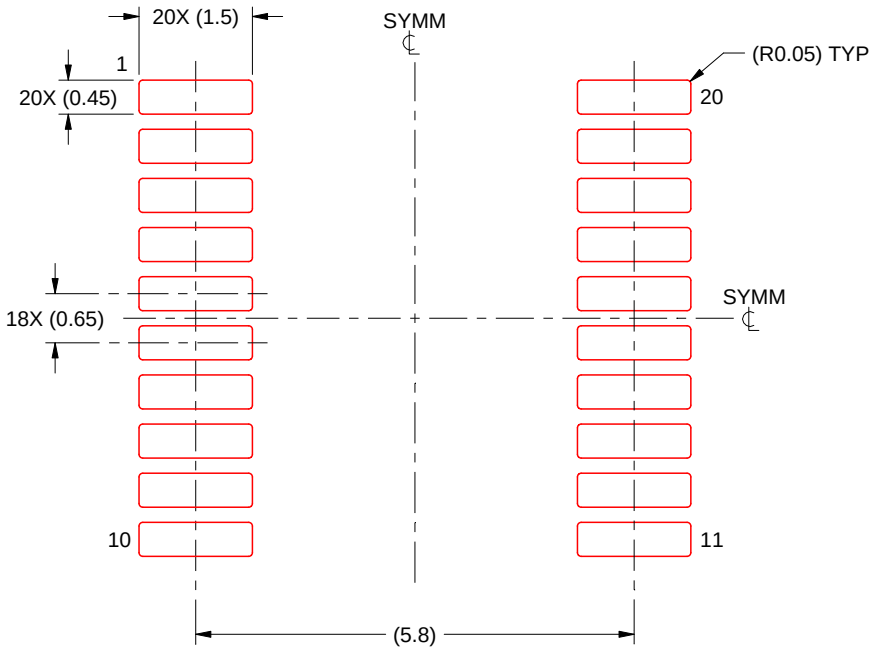


SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

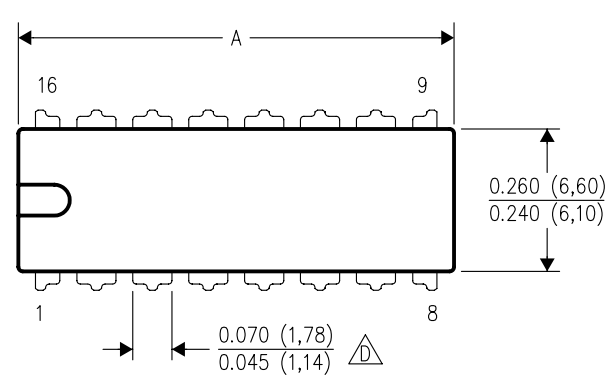
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

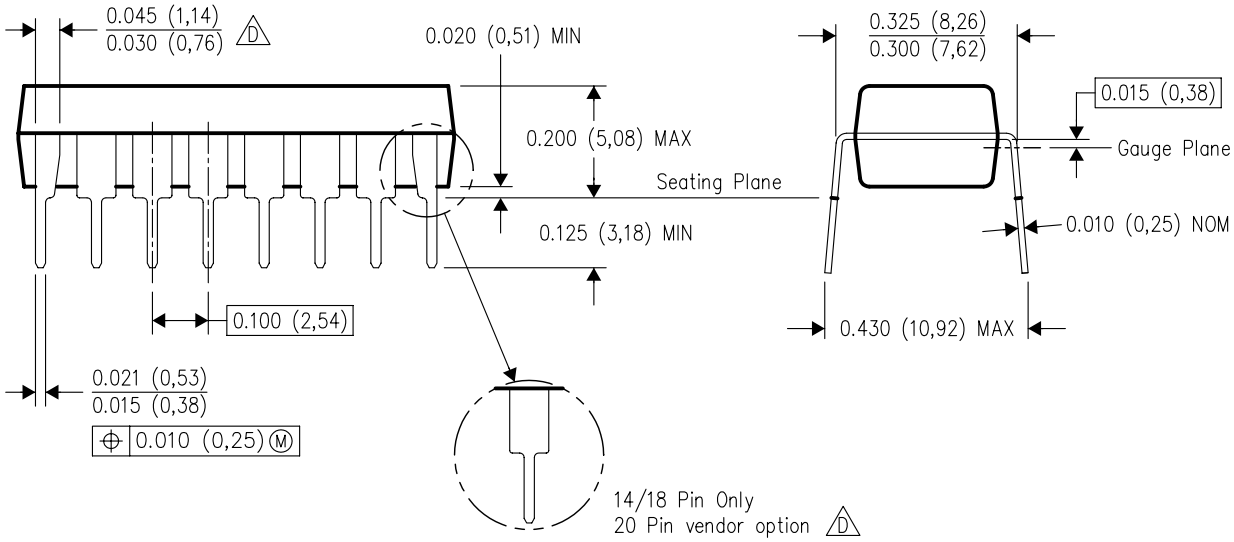
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

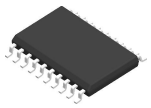


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

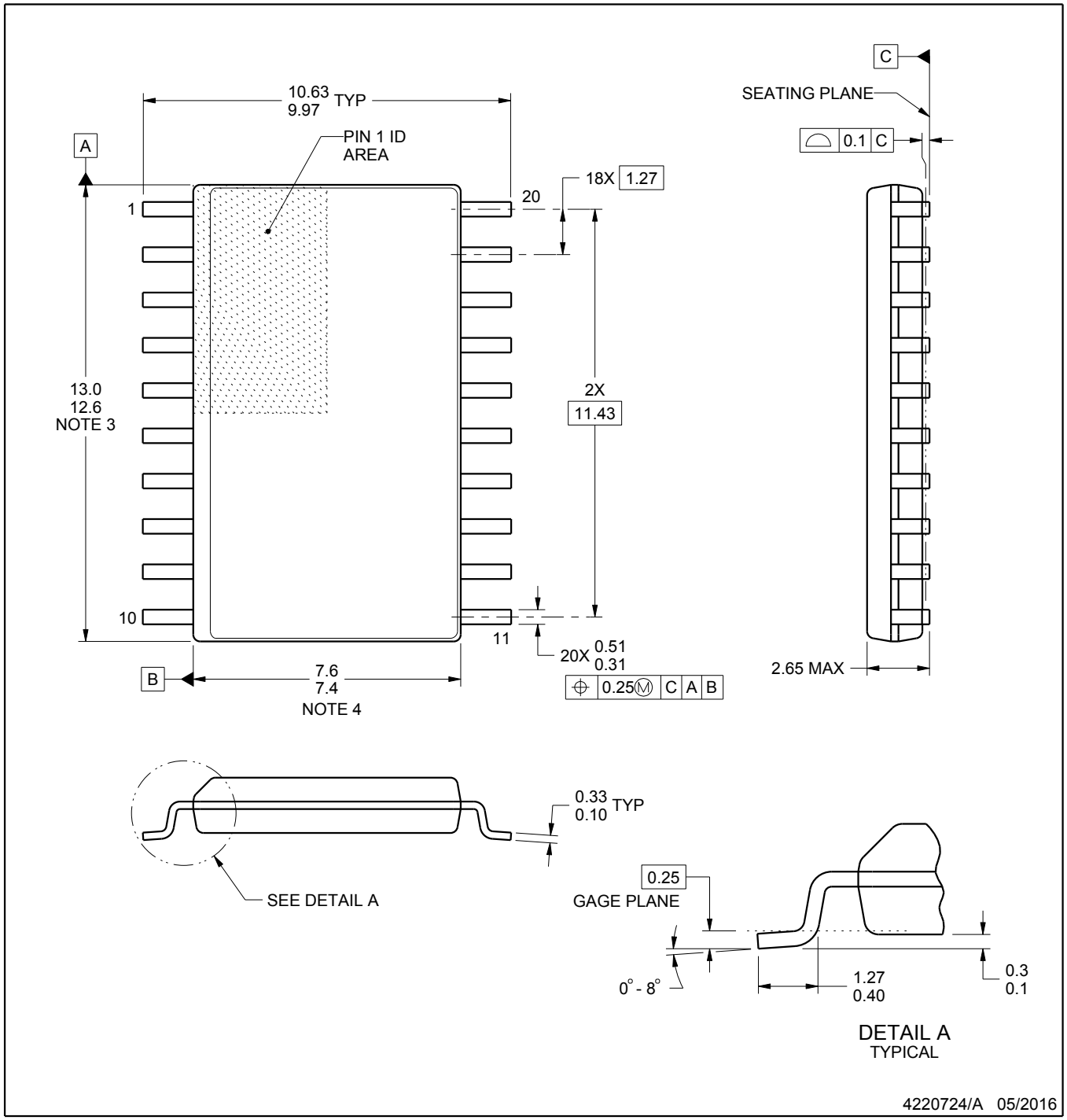


PACKAGE OUTLINE

DW0020A

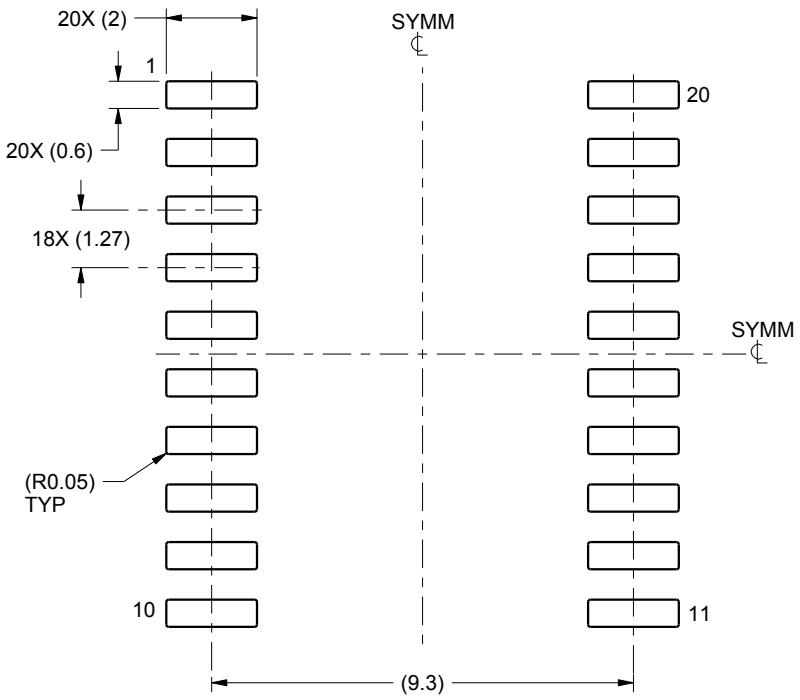
SOIC - 2.65 mm max height

SOIC

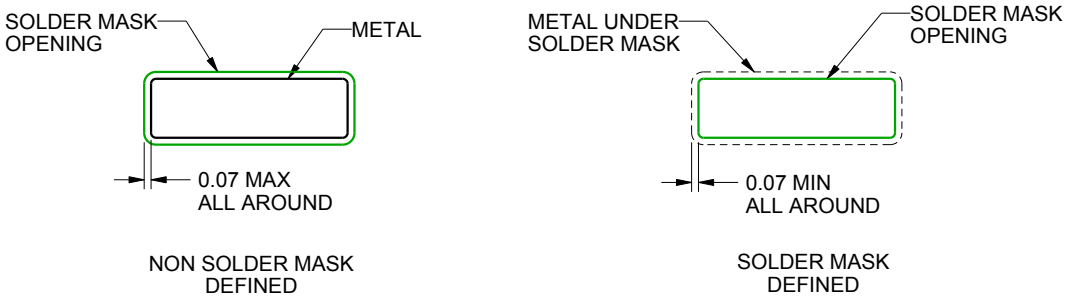


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

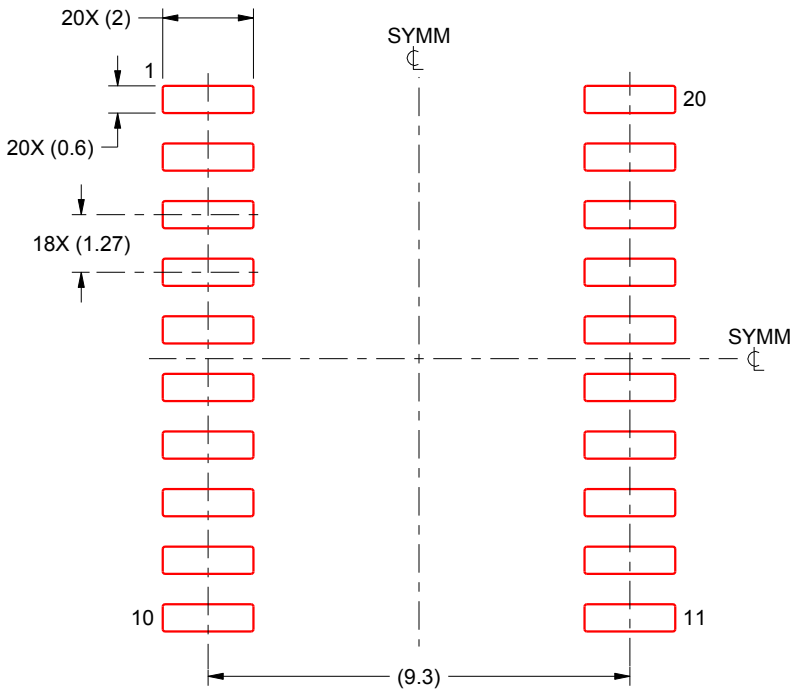


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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